Product Information Sheet

EPO-TEK® P1011-T2

Date:	February 2025	**Recommended Cure: B-Stage: 80°C/30 Minutes**
Rev:	I	**Cure: 150°C/1 Hour**
No. of Components:	Single	**Post Cure: 285°C/90 Minutes**
Mix Ratio by Weight:	N/A	
Specific Gravity:	3.29	
Pot Life:	28 Days	
Shelf Life- Bulk:	Six months refrigerated	

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: Electrically conductive, modified polyimide adhesive designed for die-attach of semiconductors and hybrid IC packaging. It is a more viscous version of EPO-TEK® P1011-2 and is a replacement for EPO-TEK® P1011-T.

Note: These are typical properties to be used as a guide only, not a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.

MATERIAL CHARACTERISTICS*:

PHYSICAL PROPERTIES:	**Cure condition:** B-Stage: 80°C/30 Minutes - Cure: 150°C/1 Hour - Post Cure: 285°C/90 Minutes	
Color (before cure):	Silver	
Consistency:	Smooth thixotropic paste	
Viscosity (23°C) @ 5 rpm:	35,050	cPs
Thixotropic Index:	3.14	
Glass Transition Temp:	Not detected	
Die Shear @ 23°C:		Kg
Degradation Temp:		°C
Weight Loss:		
@ 200°C:		%
@ 250°C:		%
@ 300°C:		%
Suggested Operating Temperature:	< 275	°C (Intermittent)
Particle Size:	≤ 20	microns

ELECTRICAL AND THERMAL PROPERTIES:		
Volume Resistivity @ 23°C:	≤ 0.0005	Ohm-cm

The data above is INITIAL only - it may be changed at any time, for any reason without notice to anyone. It is provided only as a guide for evaluation/consideration.

* These material characteristics are typical properties that are based on a limited number of samples/batches. All properties are based on the cure indicated above. Some properties may vary as manufactured quantities are scaled up to commercialized production levels.

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